ABSTRACT OF THE INVENTION

The present invention relates to enhanced protection of the active surface and the bond wires or ball array of a microelectronic device, and to thermal management of the microelectronic device as it is package with a printed circuit board (PCB) or other substrate. The enhanced protection and thermal management are accomplished with a high-temperature thermal grease that is glob topped or encapsulated over the bond wires or ball array, and the active surface of the microelectronic device. The high-temperature thermal grease exchanges heat, particularly by conduction, away from the active surface of the microelectronic device as well as away from the bond wires.

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